



TG-02F Specification

Version V1.0.0

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Document resume

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1. Product Overview

TG-02F is a bluetooth module developed by Shenzhen Ai-Thinker Technology Co., LTD. The core processor chip TG7120B(SOP16) is a highly integrated bluetooth System-level chip (SoC) with low power consumption, designed for Internet of Things (IoT), mobile devices, wearable electronic devices, smart home and other applications.

TG-02F module features a high-performance low-power 32-bit CK802 processor, 64KB SRAM, 512KB Flash, 96KB ROM, and 256 bit EFuse. In addition, TG-02F module supports SECURITY mechanism, application and OTA upgrade under BLE protocol, has a variety of unique hardware security mechanism, hardware encryption support AES algorithm.

TG-02F module provides a wealth of peripheral interfaces, including UART, PWM, ADC, I2C, SPI, PDM, DMA and up to 11 IO ports.

TG-02F module supports low power Bluetooth: BLE 5.1, BLE Mesh. Bluetooth speed support: 125Kbps, 500Kbps, 1Mbps, 2Mbps. Support broadcast extension, multi - broadcast, channel selection.

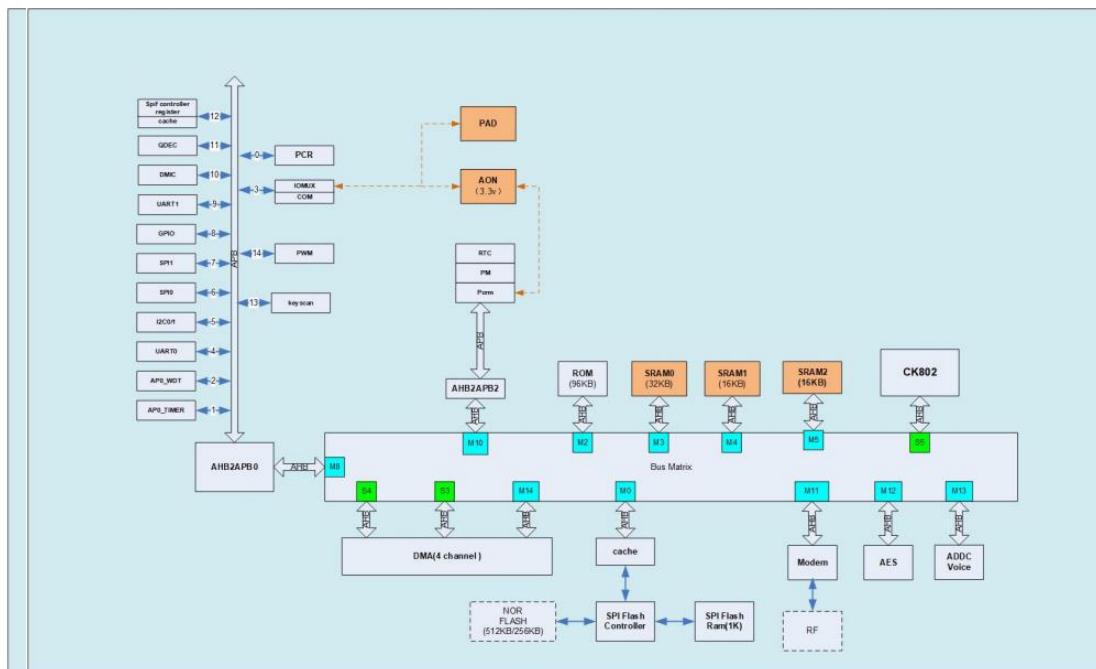


Figure 1 Main chip architecture diagram

1.1. Characteristic

- Support BLE5.1, Speed Support: 125Kbps,500Kbps,1Mbps,2Mbps
- 64 KB SRAM, 512KB flash, 96 KB ROM, 256 bit efuse
- Support UART/GPIO/ADC/PWM/I2C/SPI/PDM/DMA
- The package is SMD-20
- Multiple sleep modes are supported and the deep sleep current is less than 1uA
- Fixed universal AT instruction for quick use
- Support secondary development, integrated Windows development environment

2. Main parameters

Table 1 Description of the main parameters

Model	TG-02F
Package	SMD-22
Size	24.0*16.0*2.8(±0.2)mm
Antenna	on-board antenna
Frequency	2400 ~ 2483.5MHz
Operating temperature	-40 °C ~ 85 °C
Storage temperature	-40 °C ~ 125 °C , < 90%RH
Power supply	Support voltage 2.7V ~ 3.6V, supply current ≥200mA
Interface	UART/GPIO/ADC/PWM/I2C/SPI/PDM/DMA
IO	11
UART rate	Default 115200 bps
Bluetooth	BLE 5.1
Security	AES-128
SPI Flash	512KB

2.1. Static electricity requirements

TG-02F module is an electrostatic sensitive device. Therefore, you need to take special precautions when carrying it.



Figure 2 ESD preventive measures

2.2. Electrical characteristics

Table 2 Electrical characteristics table

Parameters	Conditions	Min.	Typical value	Max.	Unit
Power Supply	VDD	2.7	3.3	3.6	V
I/O	V _{IL} /V _I	-	-0.3/0.75VDD	-	0.25VDD/VDD+0.3
	V _{OL} /V	-	N/0.8VIO	-	0.1VIO/N
	I _{MAX}	-	-	12	mA

2.3. Bluetooth Rf Performance

Table 3 Bluetooth RF performance Table

Description	Typical value			Unit
Working Central Frequency	2400 - 2483.5			MHz
Output Power				
Model	Min.	Typical value	Max.	Unit
BLE 2Mbps	-20	8	10	dBm
BLE 1Mbps	-20	8	10	dBm
BLE 500Kbps	-20	8	10	dBm
BLE 125kbps	-20	8	10	dBm
Receive Sensitivity				
Model	Min.	Typical value	Max.	Unit
BLE 2Mbps	-	-94	-	dBm

BLE 1Mbps	-	-95	-	dBm
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2.4. Power

The following power consumption figures are based on a 3.3V power supply, an ambient temperature of 25°C, and an internal voltage regulator.

- All measurements were made at the antenna interface without SAW filter.
- All emission data are measured in TX_Burst_Test & RX_Burst_Test mode.

Table 4 Power consumption table

Model	Min.	AVG	Max.	Unit
TX_Burst_Test Power output 8dBm	-	11.5	-	mA
TX_Burst_Test Power output 5dBm	-	9.6	-	mA
TX_Burst_Test Power output 0dBm	-	8.6	-	mA
RX_Burst_Test	-	8	-	mA
Sleep (IO wake up only)	-	0.3	-	uA
Sleep(with 32KHz RTC and all SRAM retention)	-	6.5	-	uA
Power ON	-	6.24	-	mA

3. Appearance Dimensions

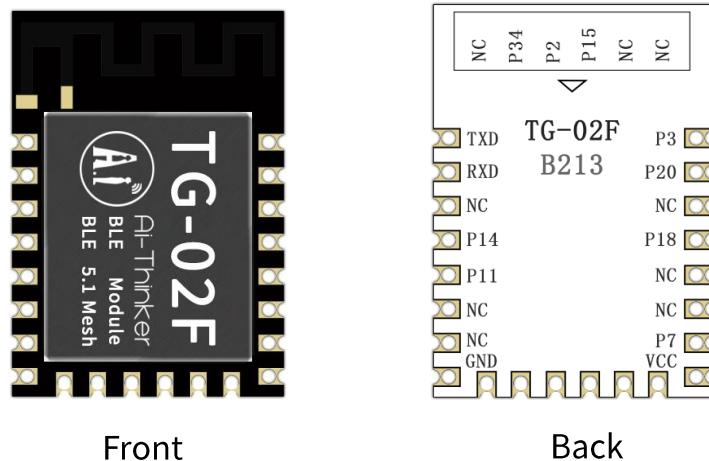


Figure 3 Appearance diagram pictures is for reference only,subject to physical objects)

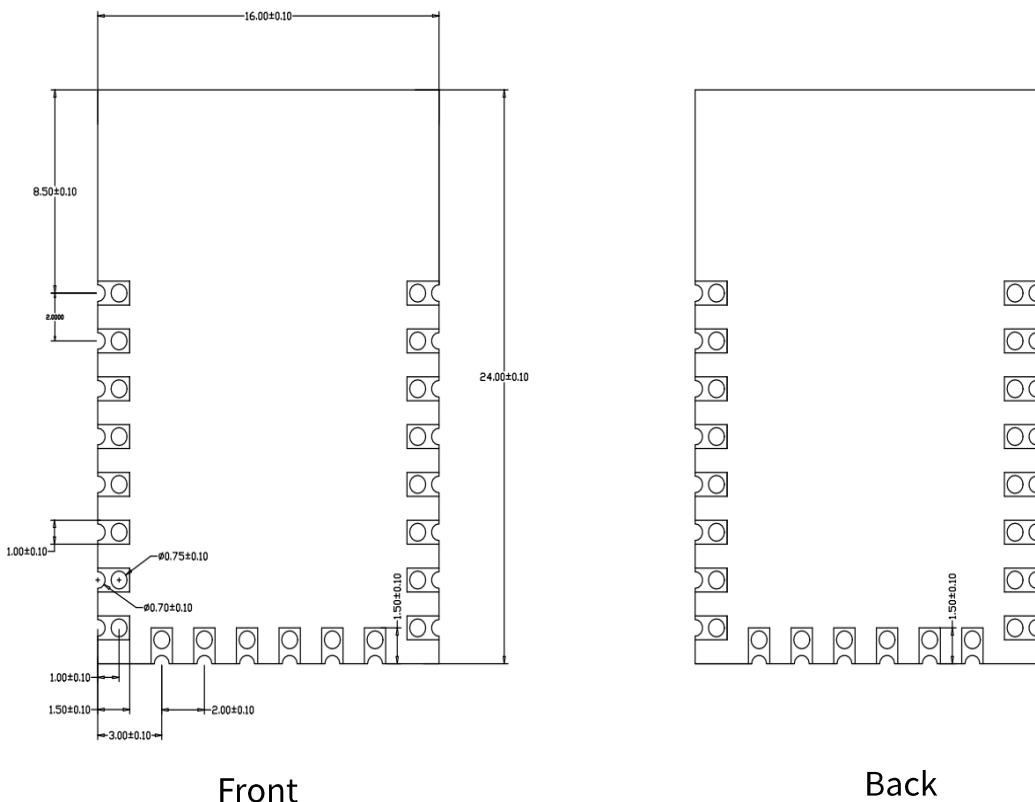


Figure 4 module size diagram

4. Pin definition

TG-02F module is connected with a total of 22 pins, as shown in the schematic diagram of pins, pin function definition table is the interface definition.

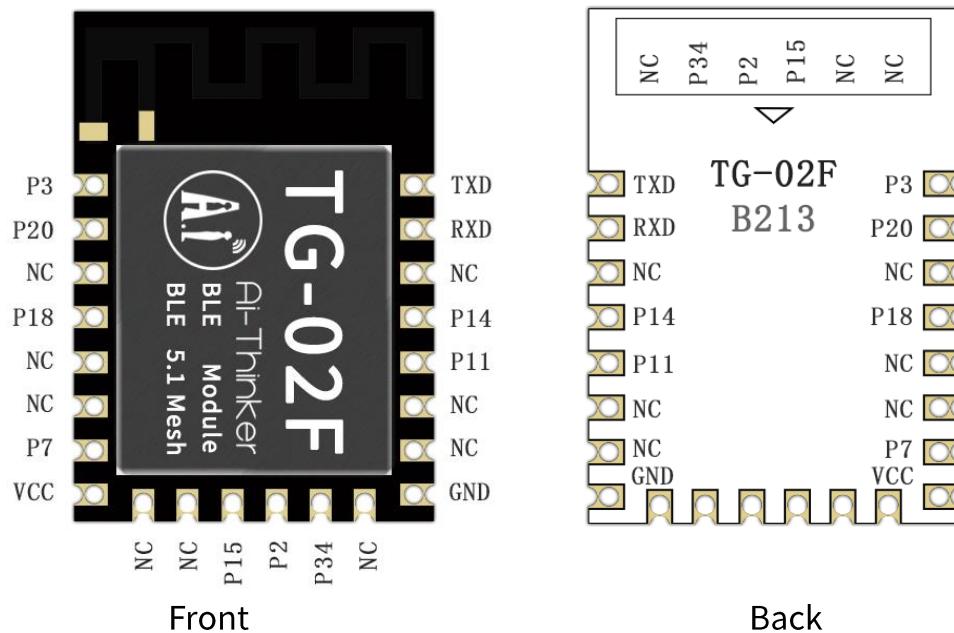


Figure 5 Schematic diagram of module pins(top view)

Table 6 Pin function definition table

No.	Name	Function
1	P3	GPIO3
2	P20	GPIO20/ ADC input 9 / PGA positive input
3	NC	NC
4	P18	GPIO18/ ADC input 7 / PGA negative input
5	NC	NC
6	NC	NC
7	P7	GPIO7
8	VCC	Power access (positive pole of power supply)
9	NC	NC
10	NC	NC
11	P15	GPIO15/ ADC input 4 / micbias output
12	P2	GPIO2
13	P34	GPIO34
14	NC	NC
15	GND	Ground(Power negative electrode)
16	NC	NC
17	NC	NC
18	P11	GPIO11/ADC input 0
19	P14	GPIO14/ADC input 3
20	NC	NC
21	RXD	RXD(GPIO10)
22	TXD	TXD(GPIO9)

5. Schematic

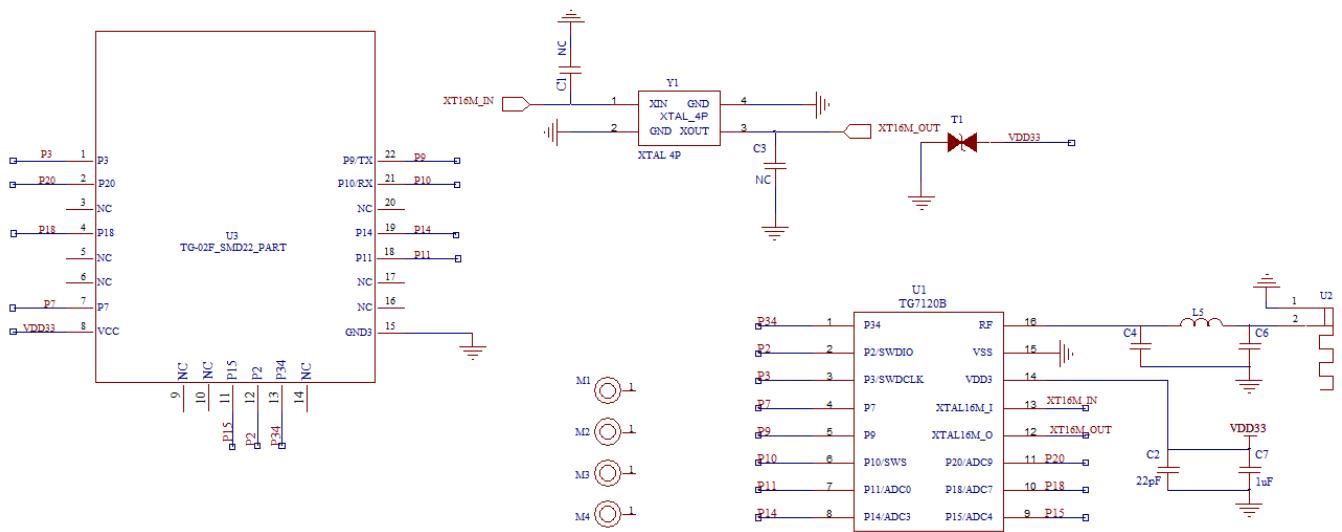


Figure 6 Module schematic

6. Antenna parameters

6.1. Test conditions for the antenna

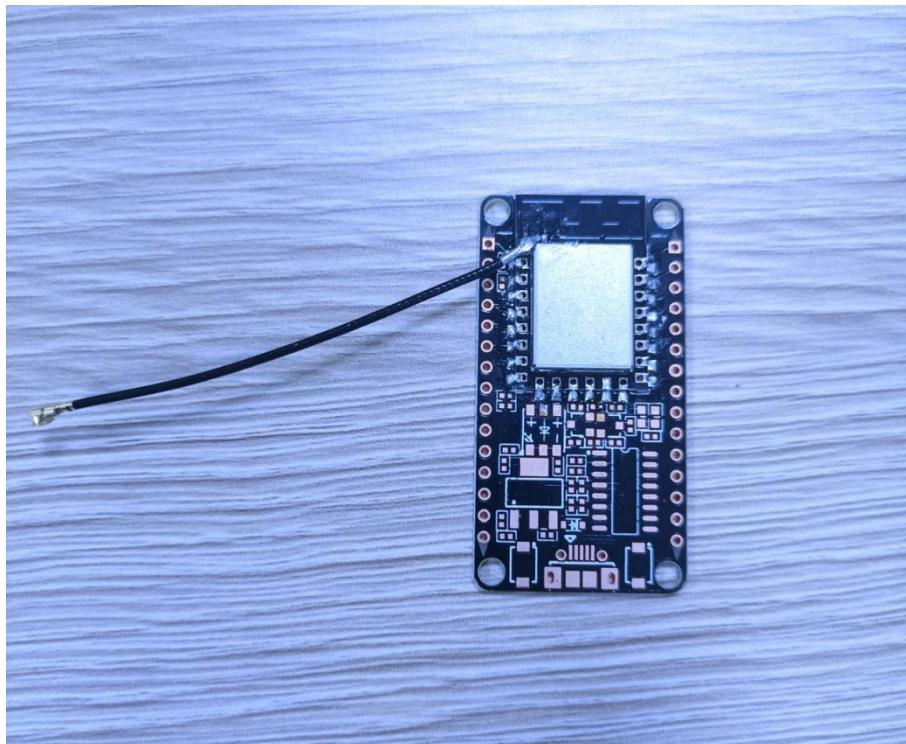


Figure 7 Antenna test conditions

6.2. Antenna S parameter

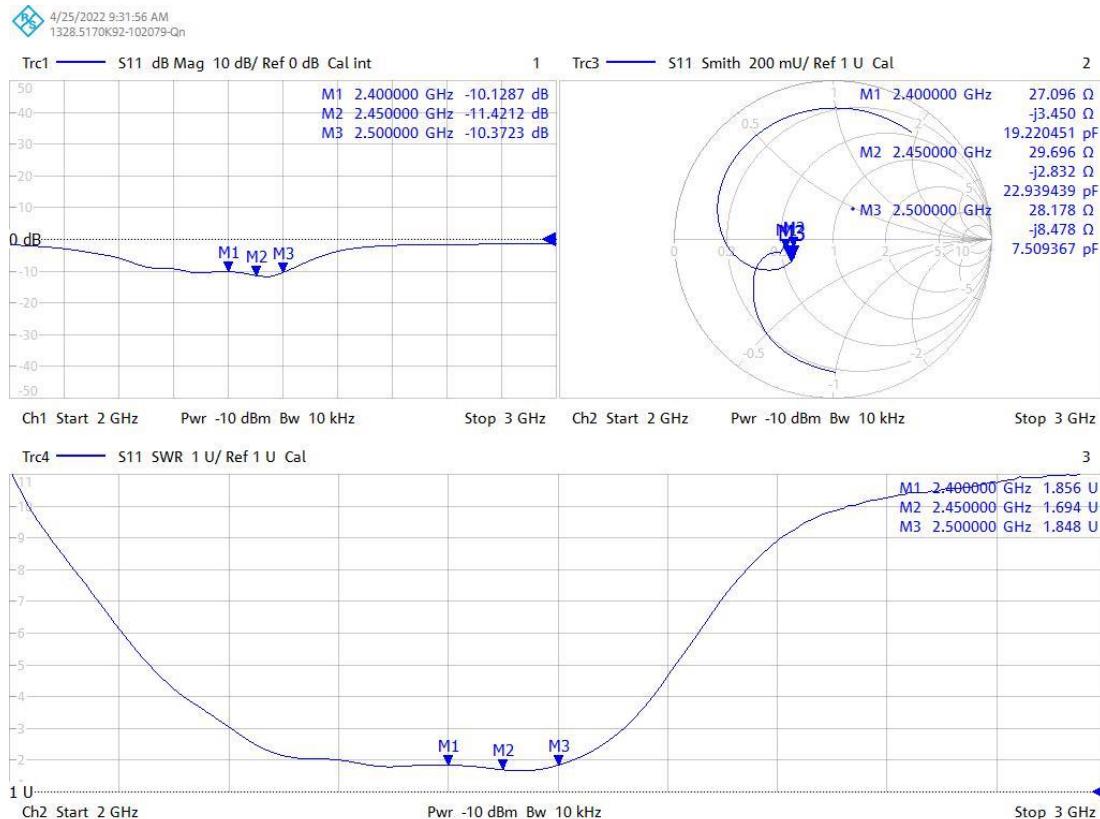


Figure 8 Antenna S parameters

6.3. Antenna Gain and Efficiency

Table 7 Antenna Gain and efficiency

Frequency ID	1	2	3	4	5	6	7	8	9	10	11
Frequency (MHz)	2400.0	2410.0	2420.0	2430.0	2440.0	2450.0	2460.0	2470.0	2480.0	2490.0	2500.0
Gain (dBi)	2.28	2.29	2.24	2.28	2.03	2.60	2.67	2.62	2.45	2.22	2.10
Efficiency (%)	59.76	60.02	59.66	59.97	56.41	63.77	64.74	64.77	63.80	61.40	60.07

6.4. Antenna Field Type Diagram

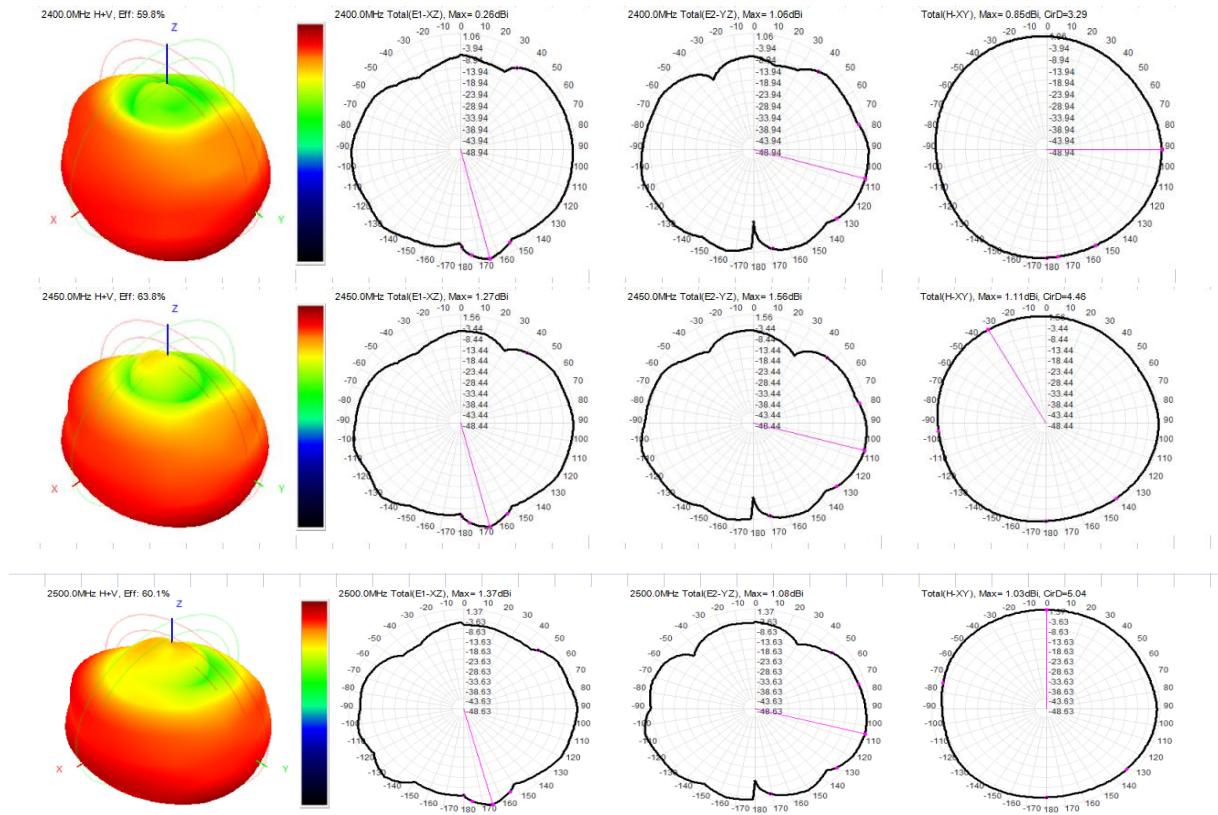


Figure 9 Antenna field type diagram

7. Design Guidance

7.1. Module application circuit

($\geq 200\text{mA}$, suggest use DC-DC or LDO independent power supply)

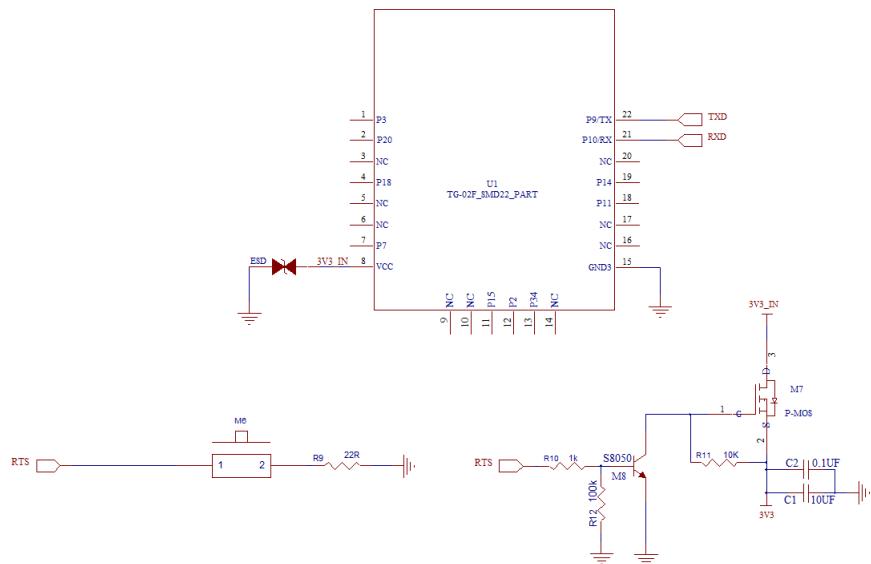


Figure 10 Application circuit diagram

Note:

- Because THERE is no reset pin for TG-02F, we realize the reset by cutting off power. A triode and PMOS can be used at the power input end to realize the reset of the module.

7.2. Antenna layout requirements

- The installation position on the motherboard suggests the following 2 ways:

Scheme 1: Put the module on the edge of the motherboard, And the antenna area extends out the edge of the motherboard.

Scheme 2: Put the module on the edge of the motherboard, and empty an area along the antenna position.

- To meet the performance of the on-board antenna, metal parts are not placed around the antenna, away from the high-frequency device.

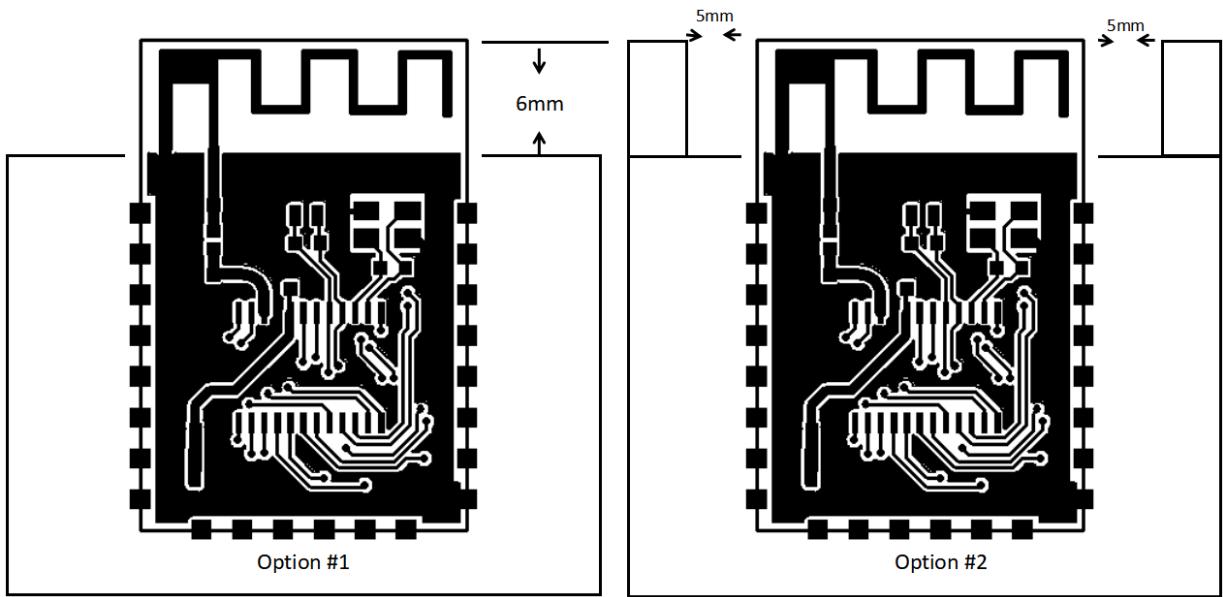


Figure 11 Antenna layout diagram

7.3. Power supply

- Recommended 3.3V voltage, peak current over 200mA.
- Power supply is recommend to use LDO; If the DC-DC is used, the ripple is recommended to be controlled within 30mV.
- DC-DC power supply circuit proposes to reserve the dynamic response capacitance to optimize the output ripple with large load changes.
- 3.3V power interface it is recommended to add ESD devices.

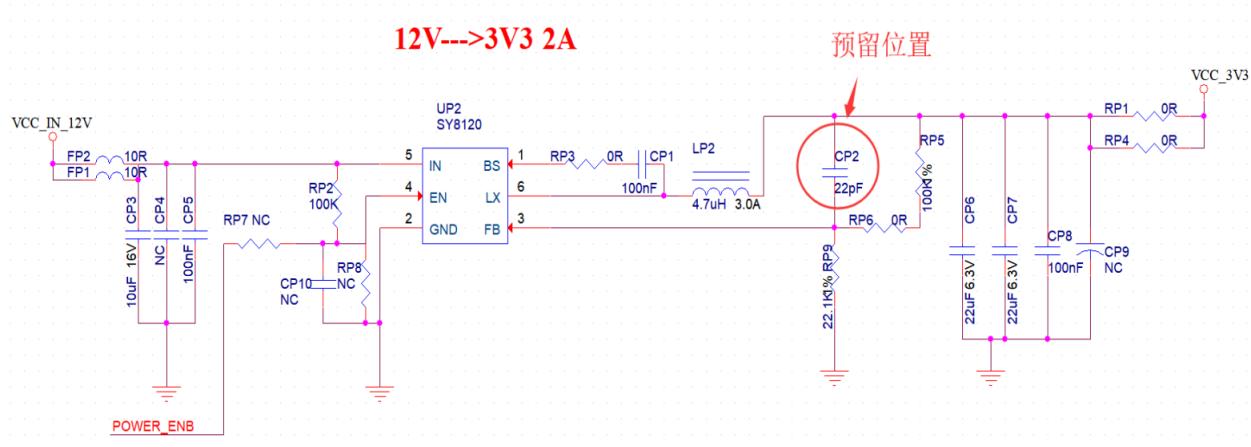


Figure 12 Dc-dc step-down circuit diagram

7.4. GPIO

- Some IO ports are introduced outside the module. If necessary, it is recommended to use a resistor of 10-100 ohms in series on the IO ports. This inhibits overshoot and makes both sides level more stable. It is helpful for EMI and ESD.
- For special I/O ports to be pulled up and down, refer to the usage instructions in the specifications, which may affect the module startup configuration.
- The IO port of the module is 3.3V. If the IO level of the main control and the module do not match, a level conversion circuit needs to be added.
- If the I/O port is directly connected to a peripheral port or terminals, for example, a pin row, reserve an ESD device near the terminal of the I/O cable.

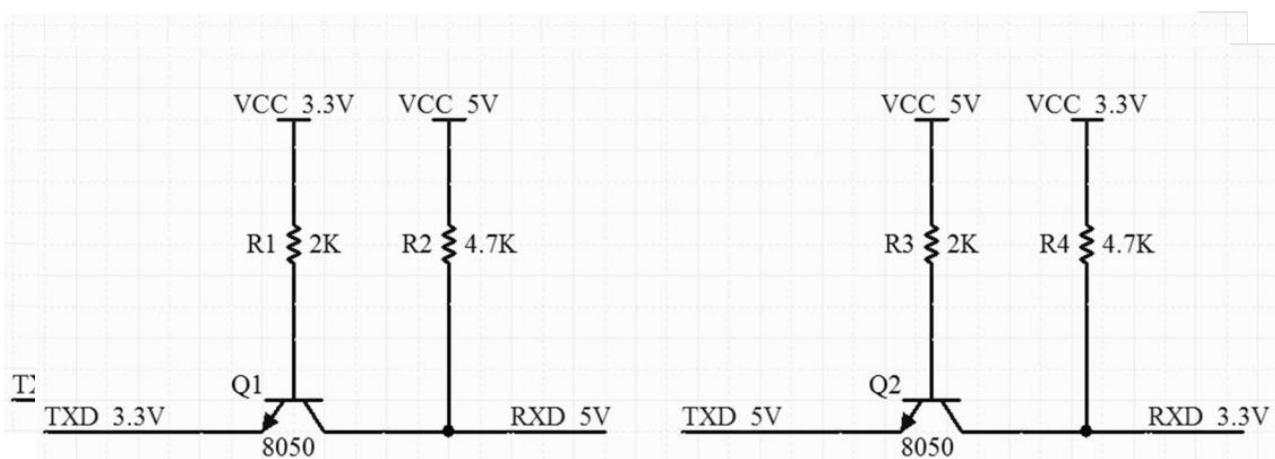


Figure 13 Level convert circuit

8. Flow welding curve diagram

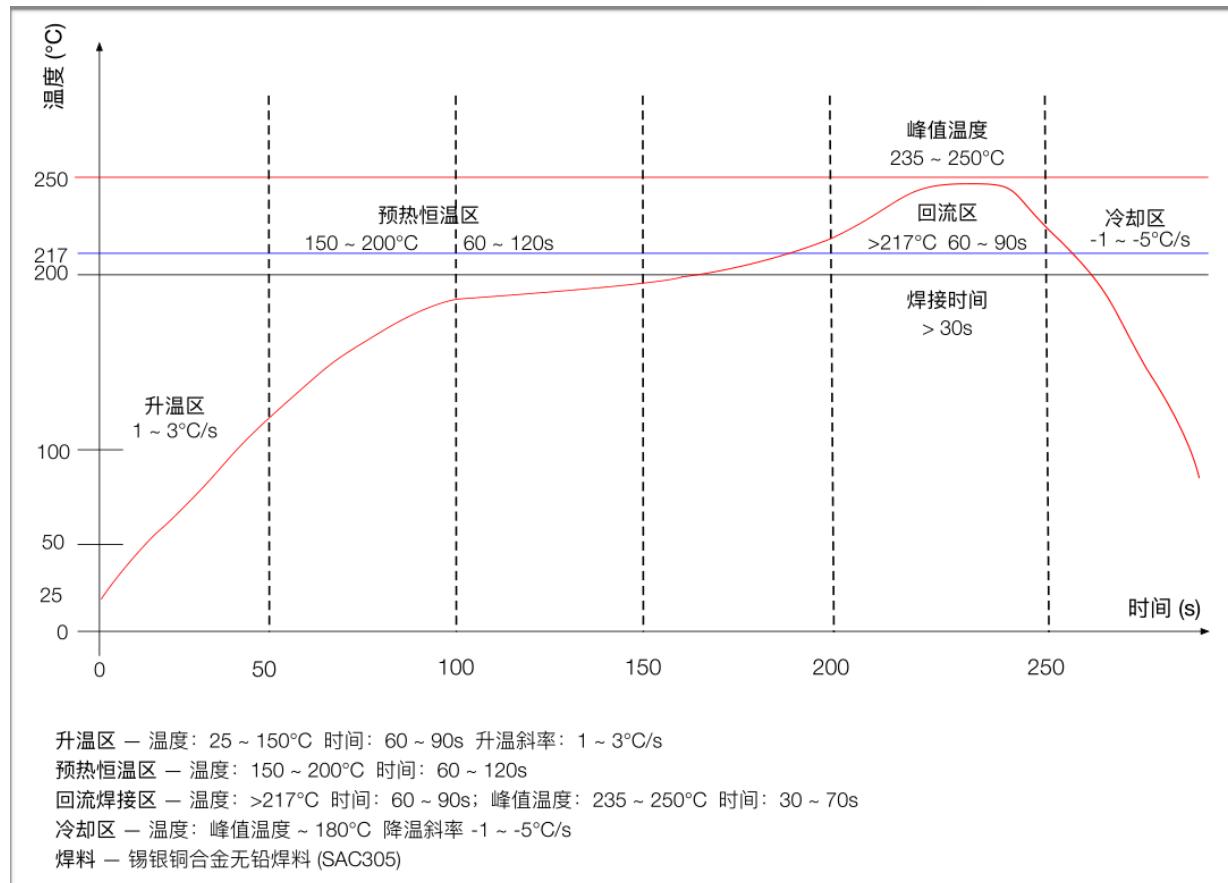


Figure 14 Flow welding diagram

9. Product related models

Table 8 Product related model list

Model	Power Supply	Package	Size	Antenna
TG-02F	2.7V ~ 3.6V, I≥200mA	SMD-22	24.0*16.0*3.1(±0.2)mm	Default on-board PCB antenna Optional external spring antenna
TG-02M	2.7V ~ 3.6V, I≥200mA	DIP-18 Gold finger plug-in	18.0*18.0*2.8(±0.2)mm	On-board PCB antenna
TG-02	2.7V ~ 3.6V, I≥200mA	SMD-20	18.6*12.2*2.8(±0.2)mm	On-board PCB antenna
TG-02F-Kit	5V, I>200mA	DIP-30	49.66*25.40(±0.2)mm	On-board PCB antenna
TG-02M-Kit	5V, I>200mA	DIP-20	32.73*28.45(±0.2)mm	On-board PCB antenna
TG-02-Kit	5V, I>200mA	DIP-19	45.54*29.93(±0.2)mm	On-board PCB antenna

Product related information : <https://docs.ai-thinker.com>

10. Product packaging information

TG-02F module was packaged in a tape, 1350pcs/reel. As shown in the below image:



Figure 15 Package and packing diagram

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WeChat mini program

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